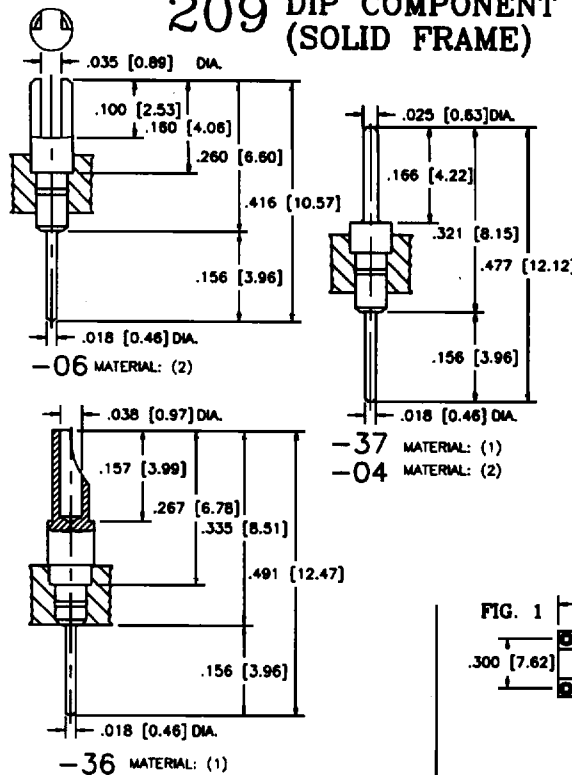


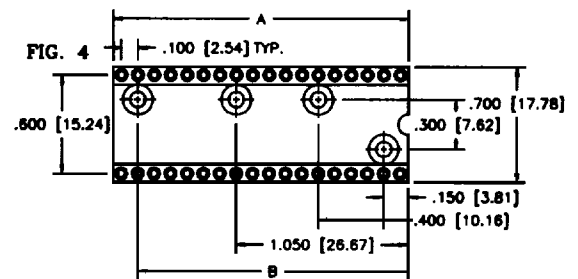
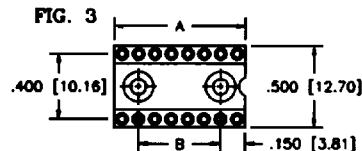
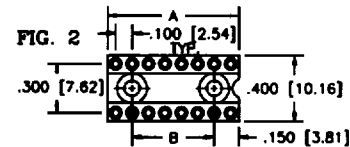
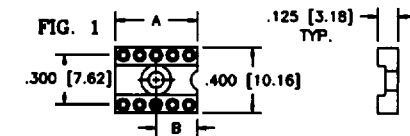
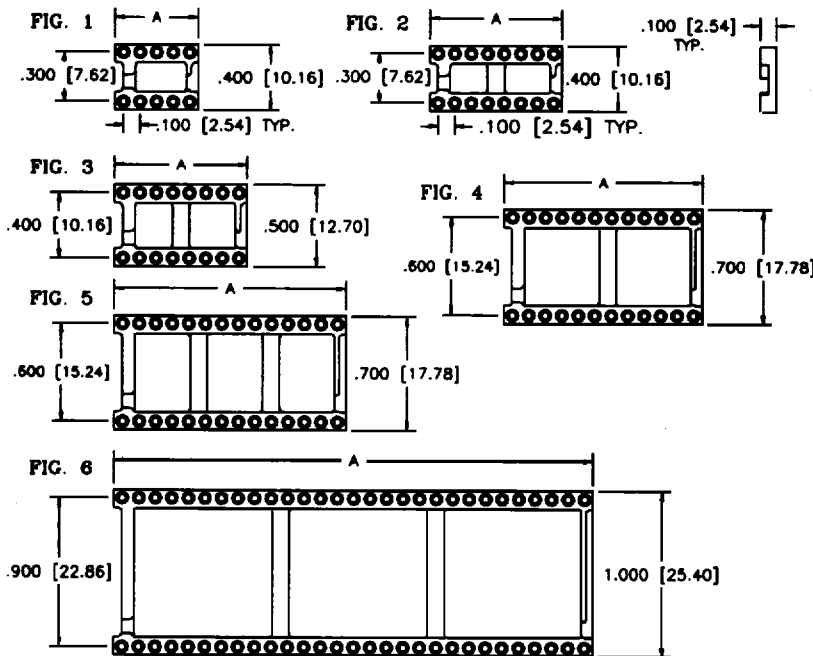
SERIES 109 DIP COMPONENT ADAPTERS/HEADERS (OPEN FRAME)

209 DIP COMPONENT ADAPTERS/HEADERS (SOLID FRAME)

SERIES 109 OPEN FRAME WAFER CHART			
	PIN	DIM "A"	
FIG. 1	6	.300 [7.62]	306
	8	.400 [10.16]	308
	10	.500 [12.70]	310
FIG. 2	14	.700 [17.78]	314
	16	.800 [20.32]	316
	18	.900 [22.86]	318
	20	1.000 [25.40]	320
	22	1.100 [27.94]	322
	24	1.200 [30.48]	324
	28	1.400 [35.56]	328
FIG. 3	16	.800 [20.32]	416
	22	1.100 [27.94]	422
	24	1.200 [30.48]	424
FIG. 4	24	1.200 [30.48]	624
	28	1.400 [35.56]	628
FIG. 5	30	1.500 [38.10]	630
	32	1.600 [40.64]	632
	36	1.800 [45.72]	636
	40	2.000 [50.80]	640
	48	2.400 [60.96]	648
	50	2.500 [63.50]	950
FIG. 6	52	2.600 [66.04]	952
	64	3.200 [81.28]	964



SERIES 209 SOLID FRAME WAFER CHART			
	PIN	DIM "A"	DIM "B"
FIG. 1	6	.300 [7.62]	.150 [3.81]
	8	.400 [10.16]	.200 [5.08]
	10	.500 [12.70]	.250 [6.35]
FIG. 2	14	.700 [17.78]	.400 [10.16]
	16	.800 [20.32]	.500 [12.70]
	18	.900 [22.86]	.600 [15.24]
	20	1.000 [25.40]	.700 [17.78]
	24	1.200 [30.48]	.900 [22.86]
	16	.800 [20.32]	.500 [12.70]
	22	1.100 [27.94]	.800 [20.32]
FIG. 3	24	1.200 [30.48]	.900 [22.86]
	24	1.200 [30.48]	.900 [22.86]
	28	1.400 [35.56]	.900 [22.86]
FIG. 4	30	1.500 [38.10]	.900 [22.86]
	32	1.600 [40.64]	.900 [22.86]
	36	1.800 [45.72]	1.650 [41.91]
	40	2.000 [50.80]	1.650 [41.91]
	40	2.000 [50.80]	1.650 [41.91]
	40	2.000 [50.80]	1.650 [41.91]



TECHNICAL SPECIFICATIONS

MATERIAL
INSULATOR GLASS FILLED POLYESTER
UL 94V-0 LISTED
TERMINAL MATERIAL: (1) BRASS PER ASTM-B16
MATERIAL: (2) PHOSPHOR BRONZE PER ASTM-B139
OPERATING TEMP. -65°C TO +125°C

ORDERING INFORMATION

109-XXX-XX-XXX-B12
209-XXX-XX-XXX-B10

SERIES
109: OPEN
209: SOLID
DIP - SPACING
NO. OF PINS
TERMINAL STYLE
FOR OPTIONAL TERMINAL STYLES
SEE TERMINAL STYLES
LOGO
INSULATOR MATERIAL
OTHER MATERIALS AVAILABLE
CONSULT FACTORY
PLATING: TERMINAL
G04: GOLD
T: TIN
TL: TIN-LEAD